

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4967179

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
PING PING OOI	07/20/2017
BOK ENG CHEAH	07/19/2017
JACKSON CHUNG PENG KONG	07/19/2017
MOOI LING CHANG	07/21/2017
WEN WEI LUM	07/20/2017
RECEIVING PARTY DATA	
Name:	INTEL CORPORATION
Street Address:	2200 MISSION COLLEGE BOULEVARD
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15982912
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	503-968-8233
Email:	kcampbell@ghmip.com
Correspondent Name:	GREEN, HOWARD, & MUGHAL, LLP
Address Line 1:	5 CENTERPOINTE DR. SUITE 400
Address Line 4:	LAKE OSWEGO, OREGON 97035
ATTORNEY DOCKET NUMBER:	01.P115515MY-US
NAME OF SUBMITTER:	KATHERINE R. CAMPBELL
SIGNATURE:	/Katherine R. Campbell/
DATE SIGNED:	05/17/2018
Total Attachments: 2	
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ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

Ping Ping OOI
Bok Eng CHEAH
Jackson Chung Peng KONG
Mooi Ling CHANG
Wen Wei LUM

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054-1549 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for Malaysia and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

"OVER-MOLDED IC PACKAGES WITH EMBEDDED VOLTAGE REFERENCE PLANE & HEATER SPREADER"

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)


which was filed on **19 June 2017** as Malaysia Application Number PI 2017702273

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below.

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in Malaysia and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in Malaysia and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.



Ping Ping OOI

20 July 2017
Date signed



Bak Eng CHEAH

19 July 2017
Date signed




Jackson Chung Peng KONG

19 July 2017
Date signed



Mui Ling CHANG

21 July 2017
Date signed



Wen Wei LUM

20 July 2017
Date signed